Feng Qin



ISSUED DAT		015/06/30 1.4	<u>) </u>
	ninary Sp Product		
Customer :			
Approved by			Notes
TIANMA Confirmed :			
Prepared by	Check	red by	Approved by

MODEL NO. : TM070RVHG01-01

This technical specification is subjected to change without notice

Fen He

Fan Jiang



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Record of Revision

Rev	Issued Date	Description	Editor
1.0	2013-02-25	•	Jim
1.1	2013-10-31	Update format	Chengfeng Tao
1.2	2013-12-11	Update the CTP AA	Chengfeng Tao
1.3	2015-04-01	Change CTP driver IC from NT11003 to SSD2543	Gang li
1.4	2015-06-30	Update drawing, add packing, Optical Characteristics	Fen He



1 General Specifications

	Feature	Spec
	Size	7.0 inch
Display Spec.	Resolution	800 RGB (H)×480(V)
	Technology Type	a-si TFT
	Pixel Configuration	RGB stripe
	Pixel pitch(mm)	0.1926x0.179
	Display Mode	Normally White
	Surface Treatment	Anti-Glare(3H)
	Viewing Direction	12 o'clock
	Gray Scale Inversion Direction	6 o'clock
	Operation Technology	Projected capacitive
	Control IC	SSD2543
	Input Method	Bare finger
TP Spec	Number of simultaneous touches	2 points
т	Minimum Touch Area(mm)	Ф6
	Finger Pitch(mm)	13
	Product structure	Glass Lens – Glass Sensor
	Interface	12C
	LCM (W x H x D) (mm)	164.90(w)×100(H)×5.7
		(D)
	Active Area(mm)	154.08(H)×85.92(V)(TFT)
Mechanical	View Area(mm)	155.24(W) x 87.12(H)(TP)
Characteristics	With /Without TSP	With CTP
	Connection Type	ZIF
	LED Numbers	24LEDs
	Weight (g)	TBD
Electrical	Interface	RGB 24 bits
Characteristics	Color Depth	16.7 M
3.16. 65.01 15.150	Driver IC	HX8264Dx1 and HX8664Bx1

Note 1: Viewing direction for best image quality is different from TFT definition. There is a 180 degree shift.

Note 2: Requirements on Environmental Protection: Q/S0002

Note 3: LCM weight tolerance: ± 5%



2 Input/Output Terminals

2.1 TFT CN1 pin assignment

Connector type: FH28-60S-0.5SH

			Connector type: FH28-60S-0.5SF				
PIN	Symbol	1/0	Description	Remark			
1	VLED+	Р	Led anode				
2	VLED+	Р	Led anode				
3	VLED-	Р	Led cathode				
4	VLED-	Р	Led cathode				
5	GND	Р	Ground				
6	VCOM	Р	Common voltage input				
7	VCC	Р	Digital power supply				
8	MODE	l	DE/SYNC mode select. H:DE mode, L:SYNC mode				
9	DE	ı	Data enable signal, active high to enable data,if not used,please pull low				
10	VSYNC	I	Vertical sync input, negative polarity,if not used,please pull High				
11	HSYNC	I	Horizontal sync input, negative polarity,if not used,please pull High				
12	B7	I	Blue data (MSB)				
13	B6	I	Blue data				
14	B5	I	Blue data				
15	B4	I	Blue data				
16	B3	ı	Blue data				
17	B2	ı	Blue data				
18	B1	ı	Blue data				
19	B0	I	Blue data (LSB)				
20	G7	ı	Green data (MSB)				
21	G6	l	Green data				
22	G5	ı	Green data				
23	G4	ı	Green data				
24	G3	ı	Green data				
25	G2	ı	Green data				
26	G1	ı	Green data				
27	G0	I	Green data (LSB)				
28	R7	ı	Red data (MSB)				
29	R6	I	Red data				
30	R5	ı	Red data				
31	R4	ı	Red data				
32	R3	I	Red data				
33	R2	I	Red data				
34	R1	I	Red data				
35	R0	ı	Red data (LSB)				
36	GND	Р	Ground				
37	DCLK	I	Clock for input data				
38	GND	Р	Ground				
P	•	•	•	•			



Model No.TM070RVHG01-00

39	LR	1	Source left or right sequence control
40	UD	1	Gate up or down scan control
41	VGH	Р	Positive power of TFT
42	VGL	Р	Negative power of TFT
43	AVDD	Р	Analog power supply
44	RESET	1	Global reset pin
45	NC	NC	
46	VCOM	Р	
47	DITHB	I	Dithering setting. H: 6bit resolution, L: 8bit resolution
48	GND	Р	Ground
49	NC	NC	
50	NC	NC	

Note1:I/O definition

I---Input, O---Output, P--- Power/Ground, NC-No connection **Table 2.1 terminal pin assignments**

2.2 U/D R/L Function Description

Scan contr	Scanning direction			
UD	LR			
GND	VCC	Up to down, left to right		
VCC	GND	Down to up, right to left		
GND	GND	Up to down, right to left		
VCC	VCC	Down to up, left to right		

2.3 TP pin assignment Connector type: FH19S-10S-0.5SH

Pin No.	Symbol	1/0	Description	Remark
1	SCL	I	I2C clock input	
2	SDA	l/O	I2C data input and output	
3	GND	Р	Ground	
4	GND	Р	Ground	
5	ATTN	I/O	External interrupt to the host	
6	GND	Р	Ground	
7	VPP	I/O	External interrupt from the host	
8	VDD	Р	CTP power supply	
9	GND	Р	Ground	
10	GND	Р	Ground	



3 Absolute Maximum Ratings

Ta = 25°C

ltem	Symbol	Min	Max	Unit	Remark
	VDD	-0.50	5.00	V	
	AVDD	-0.50	15.00	V	
Power Voltage	VGH	-0.30	42.00	V	
	VGL	-20.0	0.30	V	
	VGH-VGL	-0.30	40.00	V	
Backlight Forward Current	ILED	-	200	mA	
Operating Temperature	TOPR	-20	70	$^{\circ}$	Note2
Storage Temperature	TSTG	-30	80	$^{\circ}\!\mathbb{C}$	

Table 3.1 absolute maximum rating

Note1: The parameter is for driver IC (gate driver, source driver) only

Note2: 80° C is the surface temperature of module



4 Electrical Characteristics

4.1.1 Driving TFT LCD Panel

Ta = 25 ℃

Ite	m	Symbol	Min	Тур	Max	Unit	Remark
Voltage for lo	ogic circuit	VCC	3.00	3.30	3.60	٧	
Analog Supply Voltage		AVDD	9.88	10.4	10.92	V	
Gate On Volt	age	VGG	14.4	16	17.6	V	
Gate Off Volt	age	VEE	-7.70	-7.00	-6.30	V	
Common Ele Driving Signa		VCOM	3.93	3.95	3.97	٧	
Input Signal	Low Level	VIL	0	-	0.3xVCC	٧	
Voltage	High Level	VIH	0.7xVCC	-	VCC	V	

Table 4.1 LCD module electrical characteristics

Note1: For different LCM, the value may have a bit of difference. Note2: To test the current dissipation, use "all Black Pattern".

4.1.2 TFT Driving Backlight

Item	Symbol	Condition	Min	Тур	Max	Unit	Remark
Forward Voltage	VLED	I _F =160mA		9.6	10.8	V	
Forward Current	l _F	-	-	160	200	mA	Note 1
Backlight Power Consumption	WBL	I _F =160mA		1536	2160	mW	
Life Time	-	I _F =160mA	10,000	-	-	Hrs	Note 3

Table 4.1.2 LED backlight characteristics

Note 1: I_F is defined for one channel LED. There are total three LED channels in back light unit. Under LCM operating, the stable forward current should be inputted.

Note 2: Optical performance should be evaluated at Ta=25 °C only.

Note 3: If LED is driven by high current, high ambient temperature & humidity condition. The life time of LED will be reduced. Operating life means brightness goes down to 50% initial brightness. Typical operating life time is estimated data.

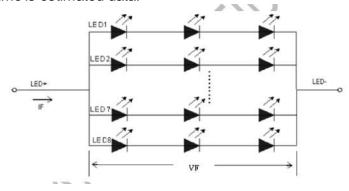


Figure 4.1.2 LED connection of backlight

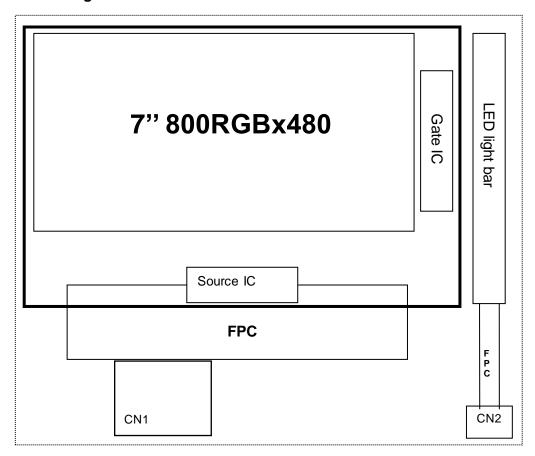


4.2 TP DC Characteristics

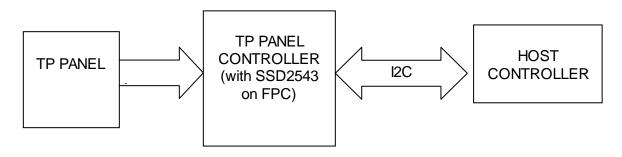
 $(T_A = 25^{\circ}C, VDD = 3.3V)$

Item	Min	Тур	Max	Unit	Note
power supply voltage	2.7	3.3	3.6	V	DC(noise should be under 100mV)
Power supply current			10	mA	

4.3.1 TFT Block Diagram



4.3.2 TP Circuit Block Diagram





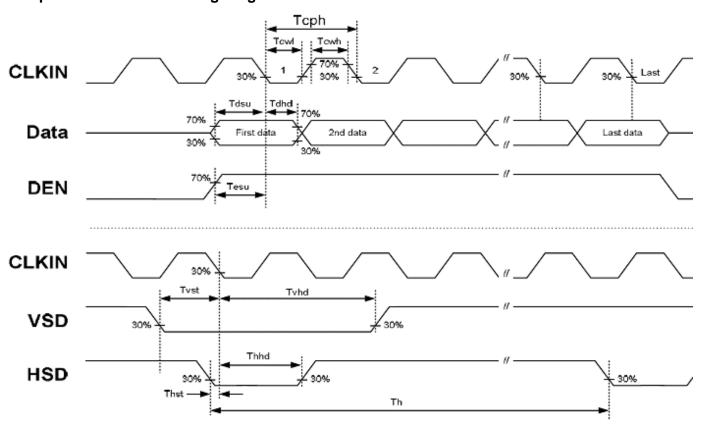
5 Timing Chart

5.1 TFT-LCD Input Timing

VCC=3.3V, GND=0V, Ta=25 $^{\circ}$ C

Parameter	Symbol	Min	Тур	Max	Unit	Remark
DCLK frequency	Fclk	28	30.0	40.0	MHz	
DCLK cycle time	Tcph	25	33.3	36	ns	
DCLK pulse width	Tcw	40%	50%	60%	Tcph	
VS setup time	Tvst	8			ns	
VS hold time	Tvhd	8	-	-	ns	
HS setup time	Thst	8			ns	
HS hold time	Thhd	8	-	-	ns	
Data setup time	Tdsu	8			ns	Data to DCLK
Data hold time	Tdhd	8	-	-	ns	Data to DCLK
DE setup time	Tesu	8	-	-	ns	
DE hold time	Tehd	8	-	-	ns	

Input Clock and Data timing Diagram:





5.2 Recommended Timing Setting Of TCON

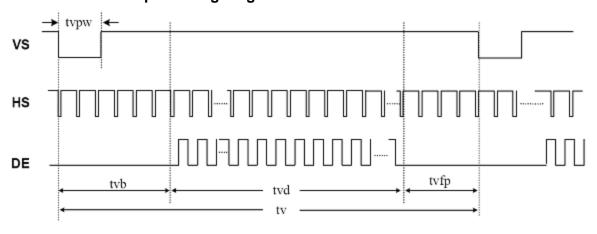
TCON (Embedded In Source IC) Input Timing (DCLK, HS, VS, DE)

VCC=3.3V, GND=0V, Ta=25°C

Parameter	Symbol	Min	Тур	Max	Unit	Remark
DCLK	Fclk	28	30	40	MHZ	
DOLK	tclk	20	33.3	36	ns	
	th	862	1056	1200	tclk	
	thd	800	800	800	tclk	
HSD	thpw	1	-	40	tclk	
	thb	46	46	46	tclk	
	thfp	16	210	354	tclk	
	tv	510	525	650	th	
	t∨d	480	480	480	th	
VSD	t∨pw	1	3	20	th	
	t√b	23	23	23	th	
	t√fp	7	22	147	th	

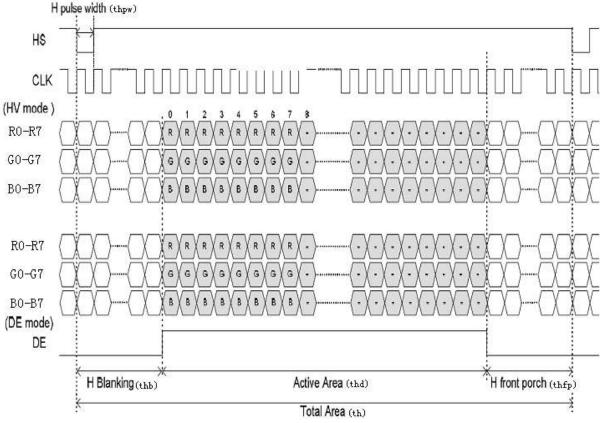
Note 1: DE timing refer to HS, VS input timing.

TCON Vertical Input Timing Diagram HV

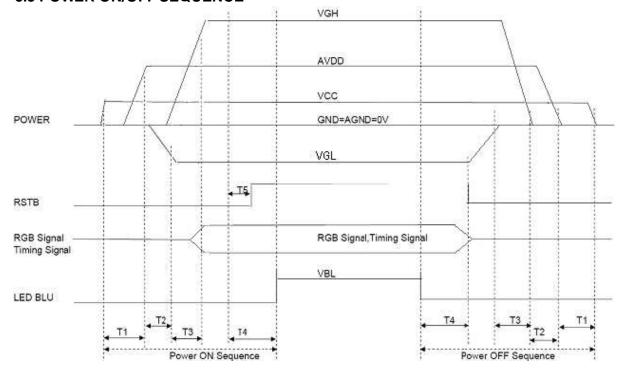




TCON Horizontal Input Timing Diagram



5.3 POWER ON/OFF SEQUENCE



Note 1: T1≥20ms, T2≥20ms, T3≥5ms, T4≥100ms, T5≥5ms.



6 Optical Characteristics 6.1 TFT Optical Characteristics

ltem		Symbol	Condition	Min	Тур	Max	Unit	Remark	
		θТ		50	60				
View Angles		θВ	CR≧10	60	70		Degree	Note 2	
view Ailgles		θL	CK = IU	60	70		Degree	Note 2	
		θR		60	70				
Contrast Ratio)	CR	θ=0°	400	500			Left/right 0° Top/bottom 5°	
Response Tim	ne	T _{ON}	25 ℃		20	35	ms	Note1 Note4	
	\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\	X		0.252	0.302	0.352			
	White	у	- -	0.271	0.321	0.371]		
	Dad	Х		0.534	0.584	0.634			
Chromoticity	Red	у	Backlight is	0.301	0.351	0.401		Note5	
Chromaticity	Green	Х	on	0.290	0.340	0.390		Note1	
	Green	У		0.536	0.586	0.636			
	Blue	Х		0.100	0.150	0.200			
	Diue	У		0.041	0.091	0.141			
Uniformity		U			75		%	Note1 Note6	
NTSC					50		%		
Luminance		L		240	300		cd/m ²	Note7	

Test Conditions:

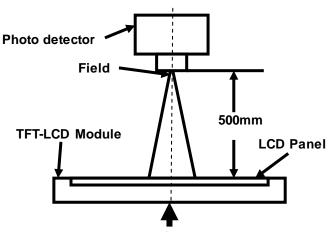
^{1.} $I_F = 160 \text{mA}$, $V_F = 9.6 \text{V}$, the ambient temperature is $25 \,^{\circ}\text{C}$.

^{2.} The test systems refer to Note 1 and Note 2.



Note 1: Definition of optical measurement system.

The optical characteristics should be measured in dark room. After 5 Minutes operation, the optical properties are measured at the center point of the LCD screen. All input terminals LCD panel must be ground when measuring the center area of the panel.

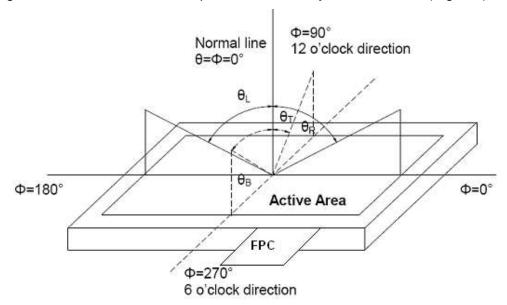


Item	Photo detector	Field	
Contrast Ratio			
Luminance	SR-3A	1°	
Chromaticity	SK-3A	'	
Lum Uniformity			
Response Time	BM-7A	2°	

The center of the screen

Note 2: Definition of viewing angle range and measurement system.

viewing angle is measured at the center point of the LCD by CONOSCOPE(ergo-80).



Note 3: Definition of contrast ratio

 $Contrast \ ratio \ (CR) = \frac{Luminance \ measured \ when \ LCD \ is \ on \ the \ "White" \ state}{Luminance \ measured \ when \ LCD \ is \ on \ the \ "Black" \ state}$

"White state ": The state is that the LCD should drive by Vwhite.

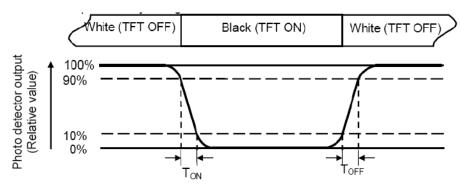
"Black state": The state is that the LCD should drive by Vblack.



Vwhite: To be determined Vblack: To be determined.

Note 4: Definition of Response time

The response time is defined as the LCD optical switching time interval between "White" state and "Black" state. Rise time (T_{ON}) is the time between photo detector output intensity changed from 90% to 10%. And fall time (T_{OFF}) is the time between photo detector output intensity changed from 10% to 90%.



Note 5: Definition of color chromaticity (CIE1931)

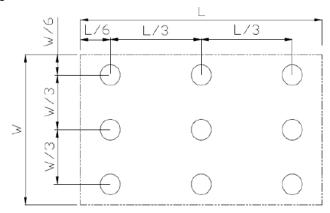
Color coordinates measured at center point of LCD.

Note 6: Definition of Luminance Uniformity

Active area is divided into 9 measuring areas (Refer Fig. 2). Every measuring point is placed at the center of each measuring area.

Luminance Uniformity (U) = Lmin/Lmax

L-----Active area length W----- Active area width



Lmax: The measured Maximum luminance of all measurement position.

Lmin: The measured Minimum luminance of all measurement position.

Note 7: Definition of Luminance:

Measure the luminance of white state at center point.



6.2 TP Optical Characteristics

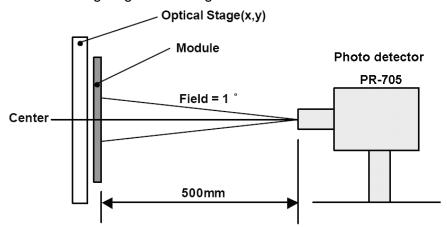
(Ta = 25 C)

No.	Item	Min.	Тур.	Max.	Unit	Remark
1	Transmission		88		%	Note 1
2	Reflectivity				%	Note 1,Note 2
3	HAZE				%	

Note1: Measuring equipments: DMS-501,PR-705. @550nm

Measuring condition:

- After stabilizing and leaving the panel alone at a given temperature for 30 min, the measurement should be executed,
 - Measuring surroundings: a stable, windless and dark room,
 - Measuring temperature: Ta=25°C,
 - 30 min after lighting the back-light.



Note2: conform to National standard GB2410—80 /ASTM D1003—61(1997)



7 Environmental/Reliability Test

No	Test Item	Condition	Remarks
1	High Temperature Operation	Ta = +70°C , 240 hours	Note1,Note6,Note7 IEC60068-2-1,GB2423.2
2	Low Temperature Operation	Ta = -20℃, 240 hours	Note1, Note7,IEC60068-2-1 GB2423.1
3	High Temperature Storage	Ta = +80°C , 240 hours	Note1, Note7,Note8 IEC60068-2-1 GB2423.2
4	Low Temperature Storage	Ta = -30℃ , 240 hours	Note1, Note7,EC60068-2-1 GB2423.1
5	High Temperature & Humidity Storage	Ta=+65°C 、RH=90%, 240 hours	Note1,Note3, Note4,Note7 IEC60068-2-78 GB/T2423.3
6	Thermal Shock/ Solder Joint Life Test	-30°C (30min) ⇔80°C (30min) ,Change	Note1,Note9 Start with cold temperature End with high temperature, IEC60068-2-14,GB2423.22
12	ESD	C=150pF \cdot R=330 Ω Air: \pm 8KV Contact: \pm 8KV 5times (Environment:15 $^{\circ}$ C ~35 $^{\circ}$ C, 30%~60%.86Kpa~106Kpa)	Note2,Note5, IEC61000-4-2 GB/T17626.2
13	Shock Test	Half Sine Wave 100G ,6ms,±X,±Y,±Z 3times for each direction	Note2
14	Drop Test(package state)	Height:60cm, 1corner,3edges,6surfaces	Note2,IEC60068-2-32 GB/T2423.8

Note1: Ts is the temperature of panel's surface.

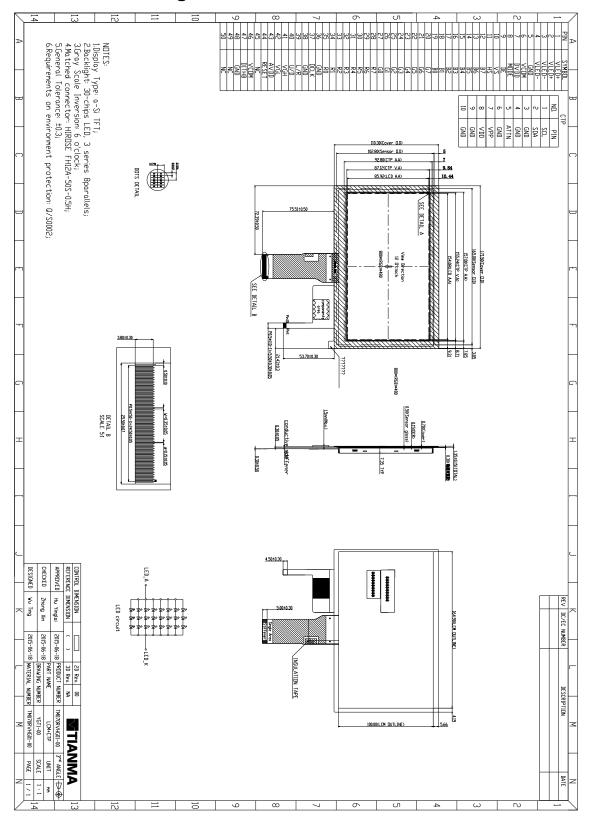
Note2: Ta is the ambient temperature of sample.

Note3: Before cosmetic and function test, the product must have enough recovery time, at least 2 hours at room temperature.

Note 4: In the standard condition, there shall be no practical problem that may affect the display function. After the reliability test, the product only guarantees operation, but don't guarantee all of the cosmetic specification.



8 Mechanical Drawing

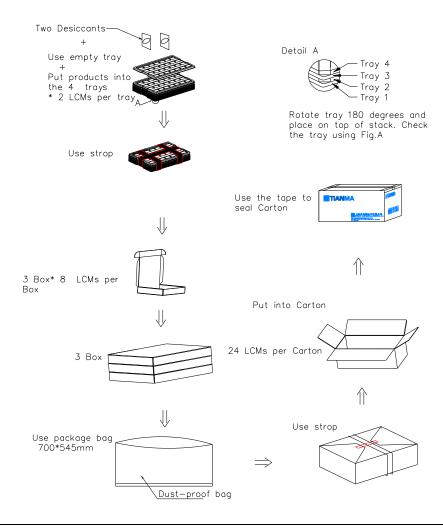




9 Packing Drawing

Per Carton

No	ltem	Model (Material)	Dimensions(mm)	Unit Weight(Kg)	Quantity	Remark			
1	LCM module	TM070RVHG01-00	164.90x100x5.7mm	TBD	24				
2	Tray	PET(Transmit)	485×330×17	TBD	15				
3	Dust-proof bag	PE	700×545	0.046	1				
4	вох	CORRUGATED PAPER	520×345×74	0.40	3				
5	Desiccant	DESICCANT	45×35	0.002	6				
6	Carton	CORRUGATED PAPER	544×365×250	1.01	1				
7	Label	PP	100×52	0.001	1				
8	Total weight	TBD±5%kg							





10 Product Inspection Criteria

10.1 Classification of defects

Major defects (MA): A major defect refers to a defect that may substantially degrade usability for product applications, including all functional defects(such as no display, abnormal display, open or missing segment, short circuit, missing component), outline dimension beyond the drawing, progressive defects and those affecting reliability.

Minor defects (MI): A minor defect refers to a defect which is not considered to be able to substantially degrade the product application or a defect that deviates from existing standards almost unrelated to the effective use of the product or its operation, such as black spot, white spot, bright spot, pinhole, black line, white line, contrast variation, glass defect, polarizer defect, etc.

10.2 Definition of inspection range

For dot defect of TFT LCD which is not smaller than 3 inches, dividing three areas to make a judgment (according to figure 1).

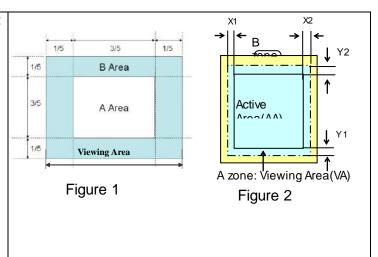
A area: center of viewing area B area: periphery of viewing area C area: Outside viewing area

For other defects, dividing two areas to make a judgment (according figure 2).

A zone: Inside Viewing area
B zone: Outside Viewing area
X1(A.A~V.A): 0mm X2(A.A~V.A):

0mm

Y1(A.A~V.A): 0mm Y2(A.A~V.A): 0mm



10.3 Inspection items and general notes

Total ineposition terms and general notes												
General notes	①Should any defects which are no shall be determined by mutual ag ② Viewing area should be the are ③ Limit sample should be prior to ④ Viewing judgment should be un ⑤ Inspection conditions Inspection distance: 250 mm (f	Inspection distance: 250 mm (from the sample) Temperature : 25±5 °C Inspection angle : 45 degrees in 12 o'clock direction (all defects in viewing area should										
	be inspected from this direction)											
	Pinhole, Bright spot, Black spot, White spot, Black line, White	The color of a small area is different from the remainder. The phenomenon doesn't change with										
	Line, Foreign particle, Bubble	voltage										
Inspectio n items	Contrast variation	The color of a small area is different from the remainder. The phenomenon changes with voltage										
HIREMIS	Polarizer defect	Scratch, Dirt, Particle, Bubble on polarizer or between polarizer and glass										
	Dot defect (TFT LCD)	The pixel appears bright or dark abnormally when display										



Model No.TM070RVHG01-00

Functional defect	No display, Abnormal display, Open or missing segment, Short circuit, False viewing direction		
Glass defect	Glass crack, Shaved corner of glass, Surplus glass		
PCB defect	Components assembly defect		

10.4 Outgoing Inspection level

Outgoing Inspection	Inspection conditions		Inspection					
standard	inspection conditions	Min.	Max.	Unit	⊒	AQL		
Major Defects	See 9.3 general notes	See 9.5			II	0.65		
Minor Defects	See 9.3 general notes	S	See 9.	5	=	1.5		
Note: Sampling standard conforms to GB2828								

10.5 Inspection Items and Criteria

				Judgmen	t standard		
	Inspec	ction items		Category	Acceptable	number	
				Category	A zone	B zone	
	Black spot,	Maak anat		Ф≦0.10	Neglected		
	White spot,	b \	В	0.10<Φ≦0.15	2		
1	Bright Spot, Pinhole, Foreign	a	С	0.15<Φ≦0.20	1	Neglected	
	Particle, Particle in or on glass,	Ф=(a+b)/2(D	0.20<Ф	0		
	Scratch on glass		Tot	al defective point(B,C)	3		
		7		W ≦ 0.01	Neglected		
	Black line, White line, and Particle	ine, and Particle Between Polarizer and	В	0.01 <w 0.03<br="" ≦="">L ≦ 3.0</w>	2		
2	Between Polarizer and		С	0.03 <w 0.05<br="" ≦="">L ≦ 3.0</w>	1	Neglected	
	glass, Scratch on glass	i i	D	0.05 <w< td=""><td>0</td><td></td></w<>	0		
	ŭ			al defective point(B,C)	3		
			Α	Ф≦0.2	Neglected		
		b	b B 0.2<Φ≦0.3		2	Neglecte	
3	Contrast	a	С	0.3<Φ≦0.4	1	d	
	variation	variation $\Phi=(a+b)/2(mm)$	D	0.4<Ф	0		
			Tot	al defective point(B,C)	3		



Model No.TM070RVHG01-00

		TFT LCD is smaller		LCD Class	Defect	A a	rea	B area	
		than 3 inches		J1033	Bright dot		 1		
				Α	Dark dot		<u>.</u> 2	1	
					Total	2		Neglecte	
					Bright dot	2		d	
				В	Dark dot		3		
		TETLODI		1.00	Total	4	<u>4</u>		
	Dot defect (if TFT LCD is	TFT LCD between 3~10.4 inches		LCD Class	Defect	A area	B area	C area	
4	used)				Bright dot	1	1	-	
				Α	Dark dot	1	2]	
					Total		1	Neglecte	
				Ъ	Bright dot	2	2	d	
				В	Dark dot Total		2 3		
		Notes:			IUIAI	()		
		Bright dot: in R \ G \ Dark dot: in R \ G \ E Defect area must be	3 or v	white dis	play figure, the	pixel app			
5	Bubble inside cell			any	/ size	none		none	
6	Polarizer defect (if Polarizer is	Scratch,damage on polarizer, Particle on polarizer or between polarizer and glass.	Ref	fer to iter	n 1 and item 2.				
	used)	Bubble, dent and	Α	(Ф≦0.3	Neglected		I	
		convex		B 0.3<Φ≦0.7		2		Neglecte	
			С		.7<Ф 0)	d d	
	Surplus	Stage surplus glass	b≦	0.3mm					
7	glass	Should not influence outline dimension and assembling							
8	Open segment or	open common	Not permitted						
9	Short circuit	Not permitted							
10	False viewing dire	Not	permitte	ed					
11	Contrast ratio une	Acc	cording to	o the limit spec	imen				
12	Crosstalk	According to the limit specimen							
13	Black /White spot	(display)	Ref	fer to iter	n 1				
14	Black /White line(display)	Refer to item 2						



			Judgment standard				
Inspection items			Category(application: B zone)			Acceptabl e number	
15	Glass defect crack	①The front of lead terminals b c	В	Crac termi	nals shoul rns and ali	des of lead d not cover	
		②Surrounding crack—non-contact side seal C b a t C b a t Inner border line of the Outer border line of the	b < Inner borderline of the seal		Max.3 defects allowed		
		3 Surrounding crack— contact side seal Inner border line of the Outer border line of the	b < Outer borderline of the seal				
		4 Corner	Α	A $a \le t, b \le 3.0, c \le 3.0$			
		w b c	В	cover	s crack sho patterns u ment mark rns.	ı and	



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		MICHELING. HWIOT UNVINGUI-UU			
	Inspection items	Judgment standard			
		Category(application: B zone)			
	Component soldering: No cold soldering short open circuit burr tin ball The flat encapsulation component position deviation must be less than 1/3 width of the pin (Pic.1); the sheet component deviation: Pin deviates from the pad and contact with the near components is not permitted (Pic.2)	Component W/2			
DCB	lead defect: The lead lack must be less than 1/3 of its width; The lead burr must be less than 1/3 of the seam; Impurities connect with the near leads is not permitted	Soldering pad Lead L1>0			
defect	Connector soldering: Soldering tin is at contact position of the plug and socket is not permitted No foundation is scald Serious cave distortion on plug and socket contact pin is not permitted	hea Base Board Soldering tin is not permit in this Soldering tin is not permit in this socket			
	Glue on root of the speaker receiver and motor lead: The insulative coat of the lead must join into the PCB; the protected glue must envelop to the insulative coat.	Glue Lead PCB Insulative coat			
	PCB defect	Component soldering: No cold soldering \ short \ open circuit \ burr \ tin ball The flat encapsulation component position deviation must be less than 1/3 width of the pin (Pic.1); the sheet component deviation: Pin deviates from the pad and contact with the near components is not permitted (Pic.2) lead defect: The lead lack must be less than 1/3 of its width; The lead burr must be less than 1/3 of the seam; Impurities connect with the near leads is not permitted PCB defect Connector soldering: Soldering tin is at contact position of the plug and socket is not permitted No foundation is scald Serious cave distortion on plug and socket contact pin is not permitted Glue on root of the speaker receiver and motor lead: The insulative coat of the lead must join into the PCB; the protected glue			



11 Precautions for Use of LCD Modules

- 11.1 Handling Precautions
 - 11.1.1 The display panel is made of glass. Do not subject it to a mechanical shock by dropping it from a high place, etc.
 - 11.1.2 If the display panel is damaged and the liquid crystal substance inside it leaks out, be sure not to get any in your mouth, if the substance comes into contact with your skin or clothes, promptly wash it off using soap and water.
 - 11.1.3 Do not apply excessive force to the display surface or the adjoining areas since this may cause the color tone to vary.
 - 11.1.4 The polarizer covering the display surface of the LCD module is soft and easily scratched. Handle this polarizer carefully.
 - 11.1.5 If the display surface is contaMinated, breathe on the surface and gently wipe it with a soft dry cloth. If still not completely clear, moisten cloth with one of the following solvents:
 - Isopropyl alcohol
 - Ethyl alcohol

Solvents other than those mentioned above may damage the polarizer. Especially, do not use the following:

- Water
- Ketone
- Aromatic solvents
- 11.1.6 Do not attempt to disassemble the LCD Module.
- 11.1.7 If the logic circuit power is off, do not apply the input signals.
- 11.1.8 To prevent destruction of the elements by static electricity, be careful to maintain an optimum work environment.
 - 11.1.8.1 Be sure to ground the body when handling the LCD Modules.
 - 11.1.8.2 Tools required for assembly, such as soldering irons, must be properly ground.
- 11.1.8.3 To reduce the amount of static electricity generated, do not conduct assembly and other work under dry conditions.
- 11.1.8.4 The LCD Module is coated with a film to protect the display surface. Be care when peeling off this protective film since static electricity may be generated.
- 11.2 Storage precautions
 - 11.2.1 When storing the LCD modules, avoid exposure to direct sunlight or to the light of fluorescent lamps.
 - 11.2.2 The LCD modules should be stored under the storage temperature range. If the LCD modules will be stored for a long time, the recommend condition is:
- Temperature : 0° C $\sim 40^{\circ}$ C Relatively humidity: $\leq 80\%$
 - 11.2.3 The LCD modules should be stored in the room without acid, alkali and harmful gas.
- 11.3 Transportation Precautions
 - 11.3.1 The LCD modules should be no falling and violent shocking during transportation, and also should avoid excessive press, water, damp and sunshine.